

SOT1717-1

FBGA529, plastic, fine-pitch ball grid array; 529 bumps; 0.8 mm pitch; 19 mm x 19 mm x 1.64 mm body

10 January 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBGA529
Package type industry code	FBGA529
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	05-01-2016
Manufacturer package code	98ASA00167D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	19	-	mm
package width	-	19	-	mm
seated height	-	1.64	1.85	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	529	-	



2 Package outline

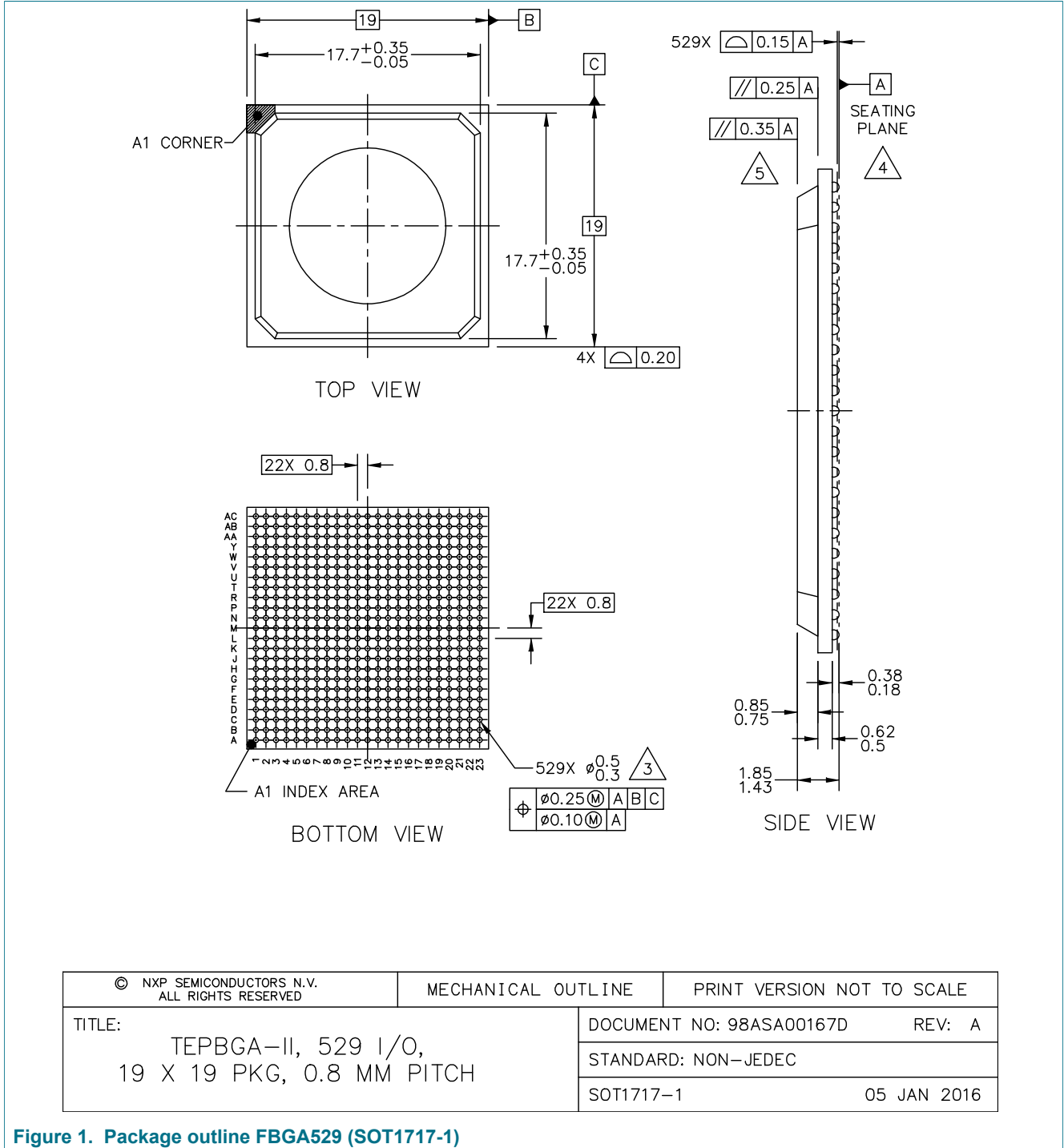


Figure 1. Package outline FBGA529 (SOT1717-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: TEPBGA-II, 529 I/O, 19 X 19 PKG, 0.8 MM PITCH	DOCUMENT NO: 98ASA00167D	REV: A
	STANDARD: NON-JEDEC	
	SOT1717-1	05 JAN 2016

Figure 2. Package outline note FBGA529 (SOT1717-1)

3 Legal information

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